

In the Claims:

Please enter the following amended claim 10:

B-1

10. (Once Amended) An integrated circuit chip comprising:

- a first interconnect metal layer;
- a first intermetallic dielectric layer situated over said first interconnect metal layer;
- a metal resistor situated over said first intermetallic dielectric layer and below a second intermetallic dielectric layer;
- a second interconnect metal layer over said second intermetallic dielectric layer;
- a first intermediate via connected to a first terminal of said metal resistor;
- a second intermediate via connected to a second terminal of said metal resistor.

In the Drawings:

Please replace Figure 11 with amended Figure 11 attached hereto. A clean copy of amended Figure 11 is also attached.